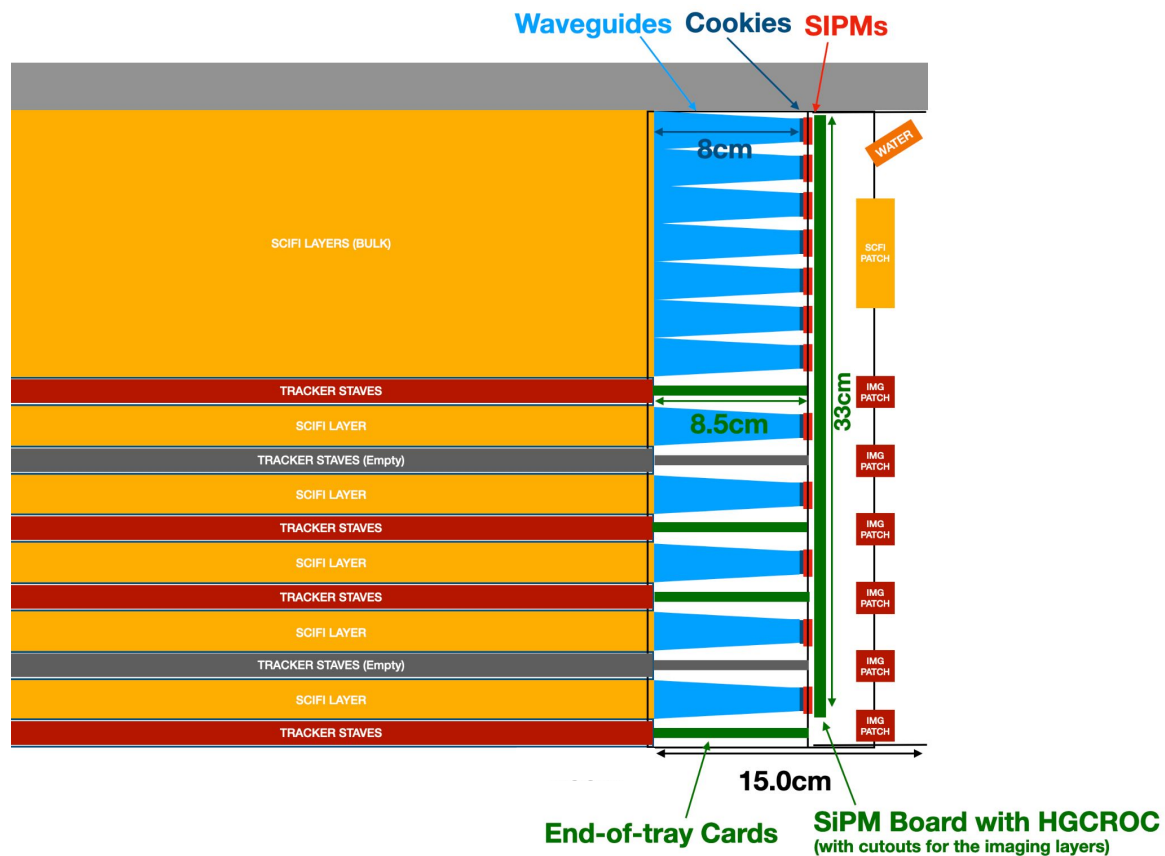
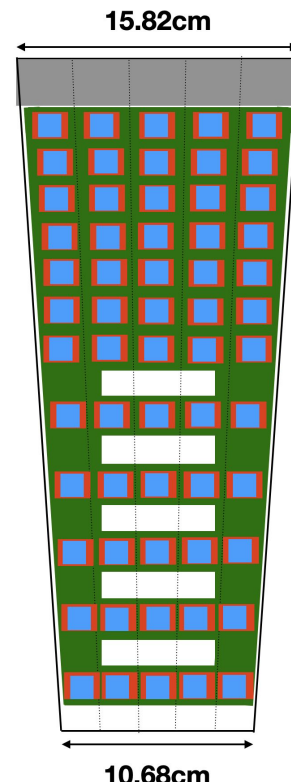


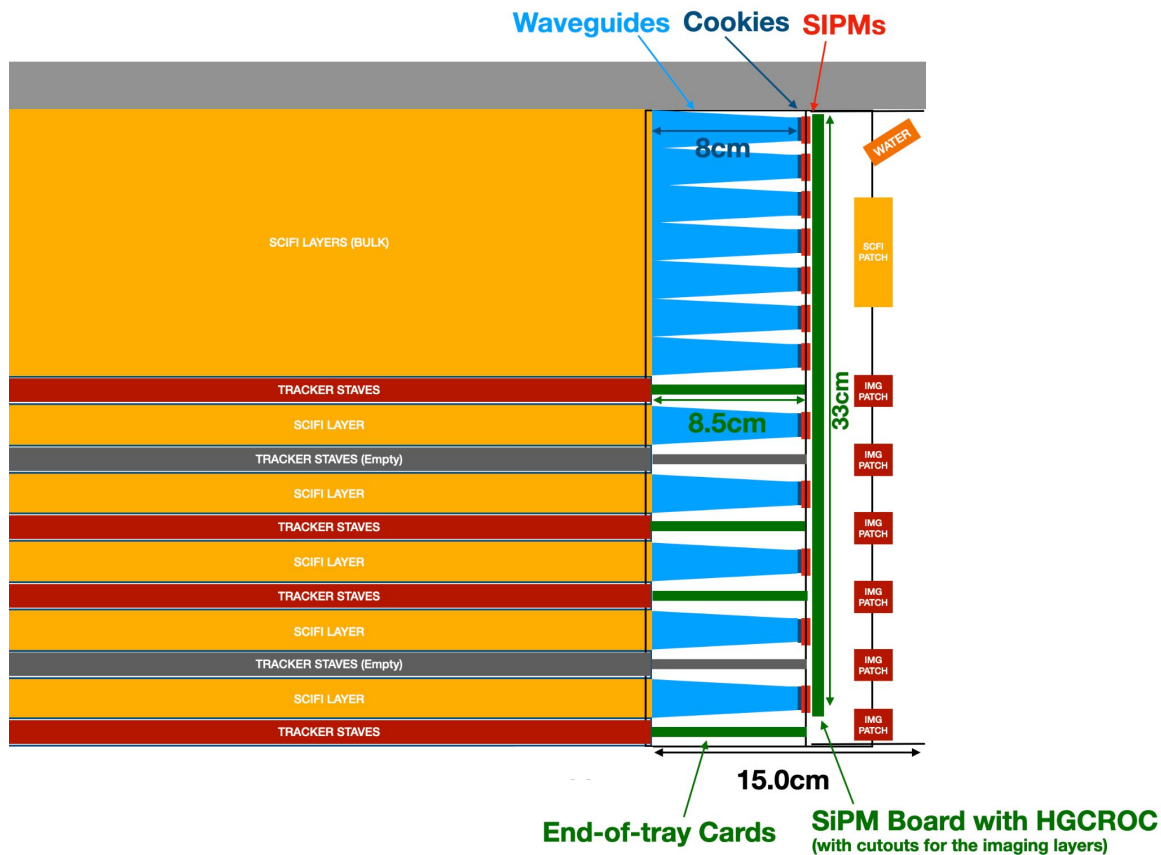
# EOSB Napking Sketch



Cross section at SiPM Board



# Status



## Updates since last meeting:

- Improved tracker layer coverage: **no space for end-of-tray card inside layers** anymore
- Updated silicon cookie size
- Back panel is patch panel
- Sector aluminum backing likely ends at the end of the sector
- Tracker CF frames likely recessed to avoid cutting

### do:

“Installable” cooling design

- Flex lines allowed?
- Install manifold(s) on back panel?

Monolithic install (single box) versus component-wise install?

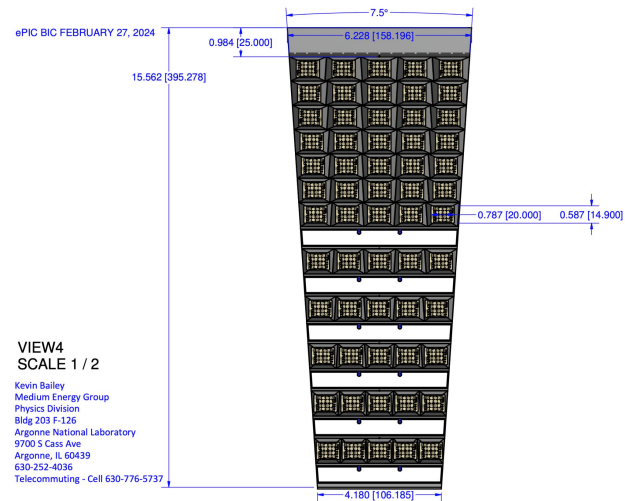
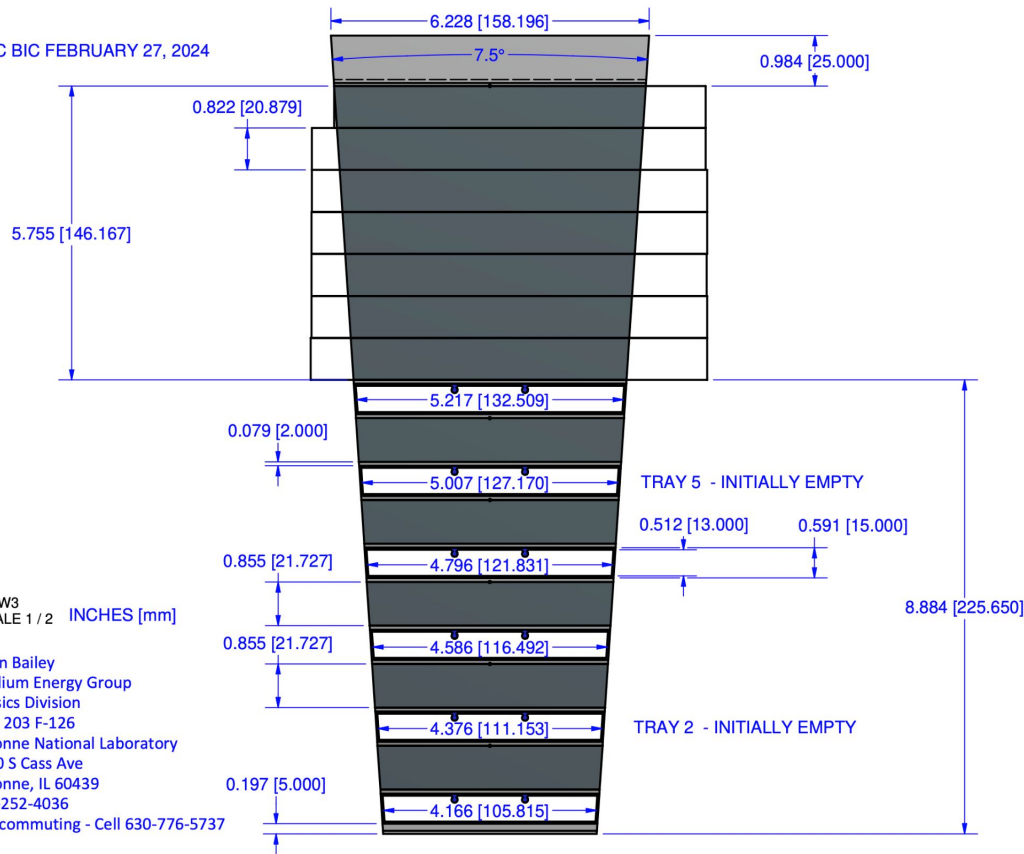
- Monolithic:** elegant install, less pieces, *but* likely need flexible cooling lines
- Components:** No flexible cooling lines needed, no loops of wires needed, *but* possible more time to install (as box assembly happens during install)

Exact SiPM board layout?

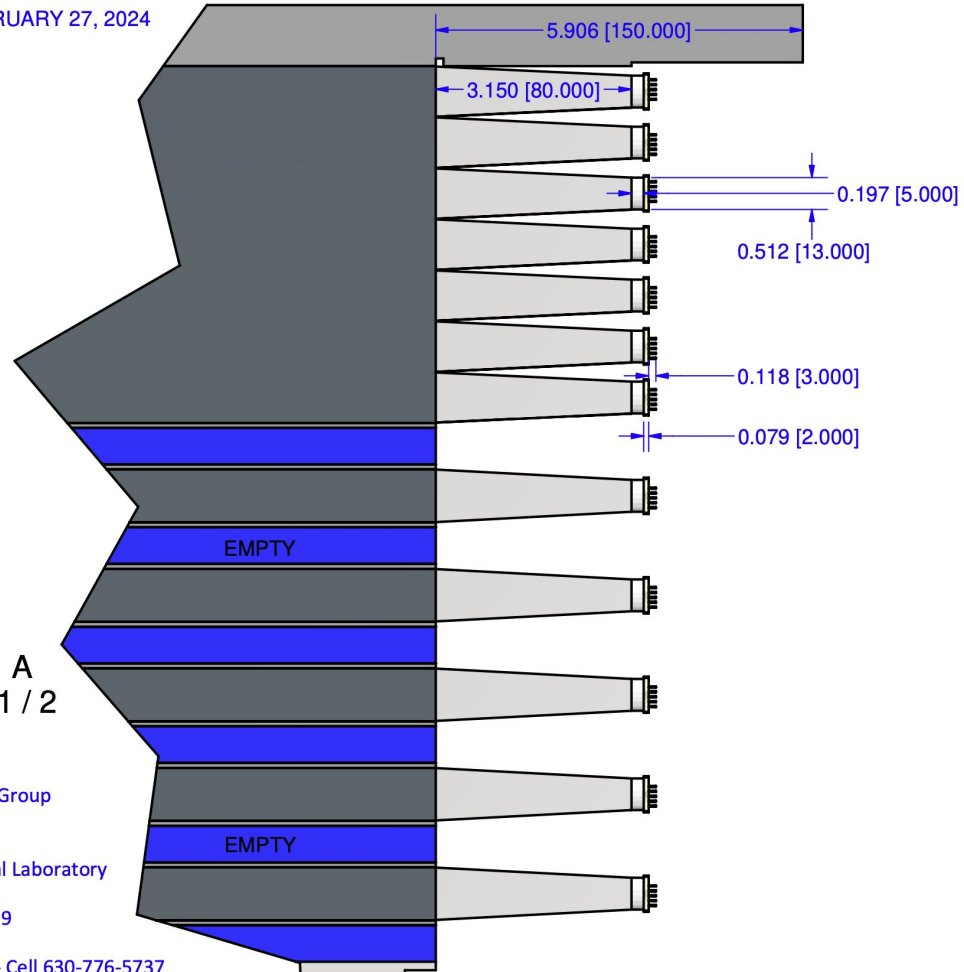
Create interface document



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DETAIL A  
SCALE 1 / 2

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# CAD Dimensions

